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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10020638	FILING DATE 12/14/2001	CLASS 257	SUBCLASS 143	GAU 2811	EXAMINER 1527 Mitchell
**APPLICANTS: Ma Bodan; Hong Sun; Tong Quinn;					
**CONTINUING DATA VERIFIED:					
** FOREIGN APPLICATIONS VERIFIED:					
PG-PUB DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no		35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO 1979.EEM	
Verified and Acknowledged Examiners's initials					
TITLE : Dual cure B-stageable underfill for wafer level					
U.S. DEPT. OF COMMERCE PAT & TM-PTO-436 (Rev. 12-94)					

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs.Drwg. Print Fig.
		X	
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner	
		PREPARED FOR ISSUE	
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